

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	40	("4276476" "4429227" "4442360" "4621194" "4725734").PN. OR ("4982096").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 08:26
L2	1	L1 and (substrate or wafer) and insulat\$4 and (detect\$4 or sens\$4) and elements and (solder or bump or pellet)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 08:27
L5	7	(US-4982096-\$ or US-4940901-\$ or US-5581084-\$ or US-6072224-\$ or US-6396043-\$ or US-5122666-\$ or US-5545899-\$).did.	USPAT	OR	ON	2006/11/08 08:33
L6	6	L5 and electric\$4 and connect\$4	USPAT	OR	ON	2006/11/08 09:43
L7	4	L5 and electric\$4 and connect\$4 and substrate and insulat\$4 and pad\$4	USPAT	OR	ON	2006/11/08 08:36
L8	7	(US-4982096-\$ or US-4940901-\$ or US-5581084-\$ or US-6072224-\$ or US-6396043-\$ or US-5122666-\$ or US-5545899-\$).did.	USPAT	OR	ON	2006/11/08 09:42
L9	1	L8 and (CT or (computer adj tomograph\$7))	USPAT	OR	ON	2006/11/08 12:33
L10	40	("4276476" "4429227" "4442360" "4621194" "4725734").PN. OR ("4982096").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 09:52
L11	9	L10 and (CT or (computer adj tomograph\$4)) and (tissue or skin or patient)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 11:38
L12	1	L5 and sulfide	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 11:38
L13	5	L5 and semiconduct\$4	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 11:44
L14	1	L5 and sulfide	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 12:04
L15	6	L5 and silicon	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 12:04
L16	471	250/370.08.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31

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L17	1097	250/370.09.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31
L18	808	250/370.11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31
L19	486	250/366.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31
L20	551	250/367.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31
L21	1938	250/338.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:31
L22	651	250/338.3.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:32
L23	167776	(substrate or wafer) and (glass or ceramic) and insulat\$4 and layers	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:33
L24	167776	L23 and (layers or stacks)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:33
L25	13370	L24 and (detect\$4 same elements)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/08 12:33
L26	72	"L25" and (CT or (computer adj tomograph\$7))	USPAT	OR	ON	2006/11/08 12:34
L34	52	L25 and L16	USPAT	OR	ON	2006/11/08 12:34
L35	154	L25 and L17	USPAT	OR	ON	2006/11/08 12:34
L36	95	L25 and L18	USPAT	OR	ON	2006/11/08 12:35
L38	13	L25 and L19	USPAT	OR	ON	2006/11/08 12:35
L39	14	L25 and L20	USPAT	OR	ON	2006/11/08 12:35
L40	58	L25 and L21	USPAT	OR	ON	2006/11/08 12:35
L41	63	L25 and L22	USPAT	OR	ON	2006/11/08 12:35

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L42	1467299	L 34 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:35
L43	21	L34 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:35
L44	46	L35 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:35
L45	21	L36 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:35
L47	9	L38 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:36
L48	1	L39 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:36
L49	22	L40 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:36
L50	32	L41 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:36
L51	16	("20020081821" "20020088537" "20020096743" "4188438" "4561005" "5218471" "5397897" "5448014" "5490628" "5567941" "5837562" "5913147" "5915168" "6297072" "6391742" "6458618").PN. OR ("6965107").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 12:36
L52	503	L25 and (pads and solder)	USPAT	OR	ON	2006/11/08 12:37
L53	169	L52 and (gap or hole) and fill	USPAT	OR	ON	2006/11/08 12:38
L55	7	L53 and L35	USPAT	OR	ON	2006/11/08 12:38
L56	4	L53 and L36	USPAT	OR	ON	2006/11/08 12:39
L58	3	L53 and L38	USPAT	OR	ON	2006/11/08 12:38
L60	2	L53 and L40	USPAT	OR	ON	2006/11/08 12:38
L61	1	L53 and L41	USPAT	OR	ON	2006/11/08 12:38
L62	6	("20020005489" "5563414" "5715292" "5834782").PN. OR ("6800857").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 12:39

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L63	22	("20020005489" "20020017611" "4810881" "5187378" "5428237" "5591963" "5612230" "5635718" "5811799" "5835045" "5841685" "5847669" "5903043" "6049074" "6075256" "6080997" "6166583" "6483184" "6548880" "6586824" "6800836" "6800857").PN. OR ("7129458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/08 12:39
S1	4	("4940901" "4982096").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/01 08:48
S2	2	(US-4982096-\$ or US-4940901-\$). did.	USPAT	OR	ON	2006/10/30 11:04
S3	40	("4276476" "4429227" "4442360" "4621194" "4725734").PN. OR ("4982096"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 12:34
S4	29	("4288264" "4317037" "4598203" "4803359" "4810881").PN. OR ("4940901"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 12:34
S5	11	("4533489" "4982096" "5091650").PN. OR ("5227633"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 12:41
S6	12	("4897788" "4969166" "5227633" "5296163" "5418377" "5440129" "5519227" "5831269" "5867554" "5981959" "6005908").PN. OR ("6823038"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 13:11
S9	21	semiconduct\$4 and support and glass and insulat\$4 and fill\$4 and elements and 250/370.11.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 13:13
S10	791	semiconduct\$4 and support and glass and insulat\$4 and fill\$4 and elements and (CT or (computer adj tomograph\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 13:13
S11	32	S10 and "250"\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 13:14

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S12	14	"5581084"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/30 13:17
S13	14	"5581084"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/30 13:23
S14	18	("4224520" "4753684" "4847489" "4885619" "5113076" "5149956").PN. OR ("5581084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/30 13:25
S19	20	("20020109100" "20030222222" "20040031930" "4893886" "5760951" "6094300" "6167173" "6429936" "6437913" "6444992").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 09:18
S20	1	S19 and coat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 09:18
S21	1	S19 and coat\$4 and filter	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 09:44
S22	1427	laser and scan\$4 and filter and coat\$4 and substrate and "359"\$. ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 09:45
S23	1288	S22 and wavelength	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 09:45
S24	3	(US-4982096-\$ or US-4940901-\$ or US-5581084-\$).did.	USPAT	OR	ON	2006/10/31 10:23
S27	3	S24 and substrate and insulat\$4	USPAT	OR	ON	2006/10/31 10:45
S29	1	"5581084" and substrate and glass	USPAT	OR	ON	2006/10/31 11:16
S30	18	("4224520" "4753684" "4847489" "4885619" "5113076" "5149956").PN. OR ("5581084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/31 10:46
S31	13	"5581084"	USPAT	OR	ON	2006/10/31 13:20
S32	18	("4224520" "4753684" "4847489" "4885619" "5113076" "5149956").PN. OR ("5581084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/31 11:18

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S33	5	S32 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/31 11:19
S34	25	"4940901"	USPAT	OR	ON	2006/10/31 13:20
S35	22	("20030128812" "4734623" "4879 464" "5721422" "5905264" "5907 156" "6069362" "6404852" "6423 974" "6590611" "6621084").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 13:33
S36	11	S35 and signal and line	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 13:36
S37	7	S35 and signal and line and cathode and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 13:37
S38	3	S35 and (signal adj line) and cathode and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/10/31 13:38
S39	277	(laser adj scan\$6) and ((interfer\$4 or photometric\$4) adj filter) and coating	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/01 08:49
S40	22	(laser adj scan\$6) and (((interfer\$4 or photometric\$4) adj filter) same coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/01 08:52
S41	12	(laser adj scan\$6) and (((interfer\$4 or photometric\$4) adj filter) same coating) and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/01 08:52
S42	3	(US-5581084-\$ or US-4982096-\$ or US-4940901-\$).did.	USPAT	OR	ON	2006/11/03 09:02
S45	29	("4288264" "4317037" "4598203" "4803359" "4810881").PN. OR ("4940901"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 09:06
S46	8	S45 and pad\$7	USPAT	OR	ON	2006/11/03 09:07
S47	8	S46 and substrate and insulat\$4 and pads	USPAT	OR	ON	2006/11/08 12:35
S49	8	S47 and elements	USPAT	OR	ON	2006/11/03 09:29

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S50	55	("4660066" "4672454" "4675730" "4807000" "4810881" "4905265" "4927771" "4940901" "4948978").PN. OR ("5043582").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 09:29
S51	44	S50 and elements	USPAT	OR	ON	2006/11/03 10:41
S53	18	S51 and pads	USPAT	OR	ON	2006/11/03 09:30
S54	10	S53 and glass	USPAT	OR	ON	2006/11/03 09:30
S55	3	S54 and fill\$5 and plastic	USPAT	OR	ON	2006/11/03 09:38
S56	2	S55 and (pads and solder)	USPAT	OR	ON	2006/11/08 12:37
S57	470	250/370.11.ccls.	USPAT	OR	ON	2006/11/03 09:42
S58	2	S56 and S57	USPAT	OR	ON	2006/11/03 09:42
S59	4	("4940901" "4982096").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/03 10:35
S60	4	substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and S57	USPAT	OR	ON	2006/11/03 10:45
S61	1	substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and (CT or (computer adj tomograph\$4)) and "250"\$.ccls.	USPAT	OR	ON	2006/11/03 10:45
S62	1	substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and (CT or (computer adj tomograph\$4) and (stack or layer)) and "250"\$.ccls.	USPAT	OR	ON	2006/11/03 10:46
S63	50	substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and (CT or (computer adj tomograph\$4) and (stack or layer))	USPAT	OR	ON	2006/11/03 11:11
S64	4	(US-5581084-\$ or US-4982096-\$ or US-4940901-\$ or US-5545899-\$).did.	USPAT	OR	ON	2006/11/03 11:00
S66	4	(\substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and (stack or layer)) and 250/370.11.ccls.	USPAT	OR	ON	2006/11/03 11:12
S67	4	(substrate and detect\$4 and insulat\$4 and element and glass and (pads same solder) and (stack or layer)) and 250/370.11.ccls.	USPAT	OR	ON	2006/11/03 11:30

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S68	29	("4288264" "4317037" "4598203" "4803359" "4810881").PN. OR ("4940901").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 11:28
S70	7	(substrate and detect\$4 and insulat\$4 and element and glass and (pads or solder) and (stack or layer)) and S68	USPAT	OR	ON	2006/11/03 11:30
S71	18	("4224520" "4753684" "4847489" "4885619" "5113076" "5149956").PN. OR ("5581084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 11:49
S72	6	250/370.11.ccls. and ((CT or (computer adj tomograph\$4)) and (substrate or wafer) and insulat\$4 and detect\$4 and glass and fill\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 12:09
S73	25	("4454424" "4491732" "4492869" "4525628").PN. OR ("4694177").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 12:08
S74	1	S73 and ((CT or (computer adj tomograph\$4)) and (substrate or wafer) and insulat\$4 and detect\$4 and glass and fill\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 12:11
S75	1	S64 and (CT or (computer adj tomograph\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/03 13:36
S84	2200	(substrate or wafer) and layers and detect\$4 and insulat\$4 same (separate or region) and solder and elements	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/06 14:57
S85	109	S84 and "250".ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/06 14:58
S86	26	S84 and 250/370\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/06 14:58
S87	4	(US-4982096-\$ or US-4940901-\$ or US-5581084-\$ or US-5545899-\$).did.	USPAT	OR	ON	2006/11/07 07:38
S88	2	S87 and element and glass	USPAT	OR	ON	2006/11/07 07:38
S89	29	("4288264" "4317037" "4598203" "4803359" "4810881").PN. OR ("4940901").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:52

EAST Search History

S90	1	(auxiliary and (substrate or wafer) and ((multi\$4 or plural\$4) adj layer) and insulat\$4 and element and (solder or pellet))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:54
S91	7	(auxiliary and (substrate or wafer) and ((multi\$4 or plural\$4) adj layer) and insulat\$4 and element and pad\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:45
S92	36	("3813587" "4238707" "4329625" "4423478" "4983884" "5362977" "5408120" "5410159" "5438210" "5461425" "5557115" "5563422" "5744829" "5862167" "5886401" "5914501" "5998232" "6016038" "6081540" "6091085" "6121127" "6133589" "6150774" "6169294" "6180960" "6236065" "6445011" "RE36747").PN. OR ("6521914").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:55
S93	2	S92 and "250"\$.cccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:56
S94	11841	((substrate or wafer) and ((multi\$4 or plural\$4) adj layer) and insulat\$4 and element and pad\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:57
S95	12	((auxiliary and (substrate or wafer) and layer) and insulat\$4 and element and pad\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:57
S96	50130	((substrate or wafer) and layer and insulat\$4 and element and pad\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:57
S97	14695	((substrate or wafer) and layer and insulat\$4 and element and pad\$5 and (solder or pellet))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:58
S98	12897	((substrate or wafer) and layer and insulat\$4 and element and pad\$5 and (solder or pellet) and (array or separat\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 07:58
S99	171	S98 and "250"\$.cccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 09:12
S10 0	16	("4425502" "4704534" "4806763" "4815199").PN. OR ("5122666").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:37

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S10 1	2	S98 and S100	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:37
S10 2	30	S98 and 250/370\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:42
S10 4	1130	((substrate or wafer) and ((multi\$4 or plural\$4) adj layer) and insulat\$4 and element and pad\$5 and (x\$1 adj ray))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:47
S10 5	798	S104 and fill\$4	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 08:47
S10 6	18	("4224520" "4753684" "4847489" "4885619" "5113076" "5149956").PN. OR ("5581084").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 09:10
S10 7	12897	((substrate or wafer) and layer and insulat\$4 and element and pad\$5 and (solder or pellet) and (array or separat\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 09:12
S10 8	30	S107 and 250/370\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/07 09:13
S10 9	7	(US-4982096-\$ or US-4940901-\$ or US-5581084-\$ or US-5545899-\$ or US-5122666-\$ or US-6396043-\$ or US-6072224-\$).did.	USPAT	OR	ON	2006/11/07 10:25
S11 0	3	S109 and (gap or hole)	USPAT	OR	ON	2006/11/08 12:38
S11 1	5	(pin or diode) and S109	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/11/07 10:48